# OLED DISPLAY SPECIFICATION





## 曜凌光電股份有限公司 Raystar Optronics, Inc.

T: +886-4-2565-0761 | F: +886-4-2565-0760 sales@raystar-optronics.com | www.raystar-optronics.com

# SPECIFICATION

Model No:

# REX012832GYAP3N00000

### **CUSTOMER:**

APPROVED BY									
PCB VERSION									
DATE									
FOR CUSTOMER USE	FOR CUSTOMER USE ONLY								
SALES BY	APPROVED BY	CHECKED BY	PREPARED BY						

Release DATE:

**APPROVAL FOR SPECIFICATIONS ONLY** 

APPROVAL FOR SPECIFICATIONS AND SAMPLE



## **Revision History**

VERSION	DATE	REVISED PAGE NO.	Note
0	2018/08/14		First release
A	2018/11/15		Sample spec
В	2018/11/27		Modify Static
			electricity test
			Content of Test
С	2019/09/02		Modify Precautions in
			use of OLED
			Modules
D	2019/12/18		Modify Reliability Test
			measurement
			conditions &
			Inspection
			specification:
			" Accept no dense"
			modify to "ignore"&
			Precautions
			&Interface Pin
			Function
E	2020/08/27		Modify Inspection
_			specification
F	2020/11/18		Modify Storage
			Precautions





# Contents

- 1.General Specification
- 2.Module Classification Information
- 3.Interface Pin Function
- 4.Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
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- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



### **1.General Specification**

The Features is described as follow:

- Module dimension: 50.50 x 15.75 x 2.01 mm
- Active area: 42.22 x 10.54 mm
- Dot Matrix: 128 x 32
- Pixel size: 0.308 x 0.308 mm
- Pixel pitch: 0.33 x 0.33 mm
- Display Mode: Passive Matrix
- Duty: 1/32 Duty
- Display Color: Yellow
- IC: SSD1307ZD
- Interface: SPI,I2C
- Size: 1.71 inch



## **2.Module Classification information**

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	Е	Х	01283	2 G	Y	A	Р	3	N	0	0	0	00
· · · · · ·													
1			/star Opt	ronics Ind	C.							X	
2	E : C	DLED											
3	Display Type X : COG H					H :	COB ( COG - TAB		C				
4	Dot N	∕latrix ∶	128*32	2									
5	Serie	es											
6	Emitt	ting Co	lor	A : AmberR : RedB : BlueW : WhiteG : GreenY : YellowS : Sky BlueX : Dual Color				C :	C : Full Color				
7	Pola	rizer		P∶With A∶Anti-				out Pol	arizer				
8		ay Mo		P:Pass				ive Ma	atrix				
9		er Volta		3:3.0~		•		22					
10	Touc	h Pane		N : With		uch pa	nel; T:	With t	ouch p	anel			
11	Prod	0 : Standard         1 : Daylight Readable         2 : Transparent OLED (TOLED)         3 : Flexible OLED (FOLED)         4 : OLED Lighting					100						
12		ection C	Grade	0 : Standard 2 : B grade C : Automotive grade Y : Consumer grade					5				
13	Optic			0 : Defa				H : Ho	t bar F	PC; D	: Dem	o Kit	
14	Seria	al No.		Serial n	umber(	(UU~ZZ	<u>(</u> )			10	20	00,	



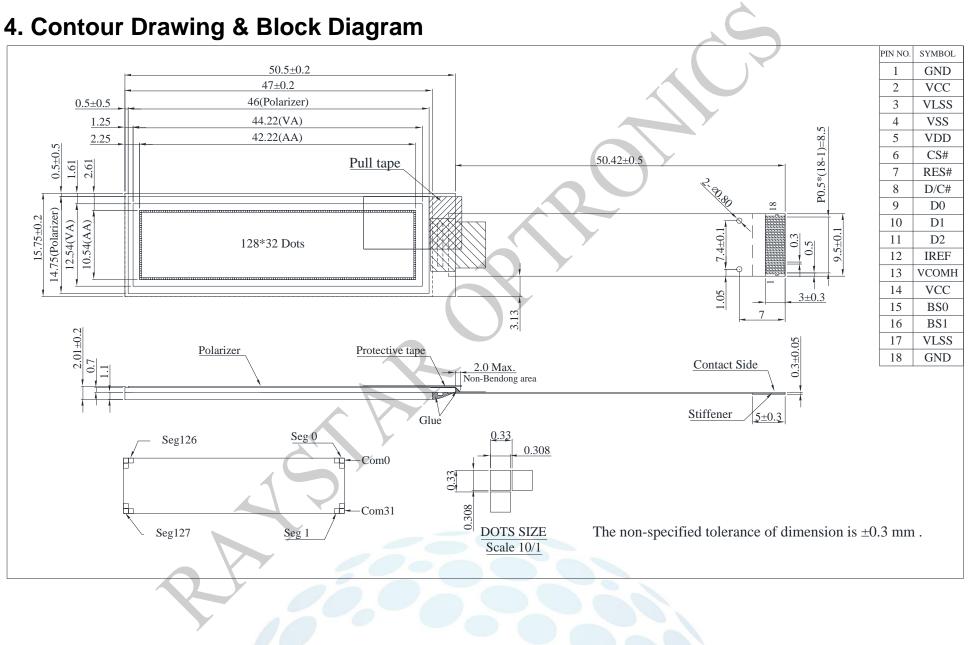
### **3.Interface Pin Function**

No.	Symbol	Function
1	N.C. (GND)	Dummy Pin This is dummy pin. Do not group or short NC pins together.
2	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
3	VLSS	This is an analog ground pin. It should be connected to VSS externally
4	VSS	This is a ground pin.
5	VDD	Power Supply for Logic
6	CS#	The chip select input. (active LOW)
7	RES#	Power Reset for Controller and Driver
8	D/C#	This is Data/Command control pin. When it is pulled HIGH (i.e. connect to VDD), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to VSS.
9~11	D0~D2	Host Data Input / Output Bus When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL.
12	IREF	This is segment output current reference pin. A resistor should be connected between this pin and VSS to maintain the IREF current at 10uA.
13	VCOMH	The pin is for COM signal deselected voltage level. A capacitor should be connected between this pin and VSS.
14	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.



		Communicating Pro		on input. See the fo	ollowing table:			
			BS0	BS1				
	AF 40 BS0	I2C	0	1				
15,16	BS1	3-wire SPI	1	0	1			
	001	4-wire SPI	0	0				
		Note (1) 0 is connected to V (2) 1 is connected to V						
17	VLSS	This is an analog g	This is an analog ground pin. It should be connected to VSS externally.					
18	N.C. (GND)	Dummy Pin This is dummy pin. Do not group or short NC pins together.						

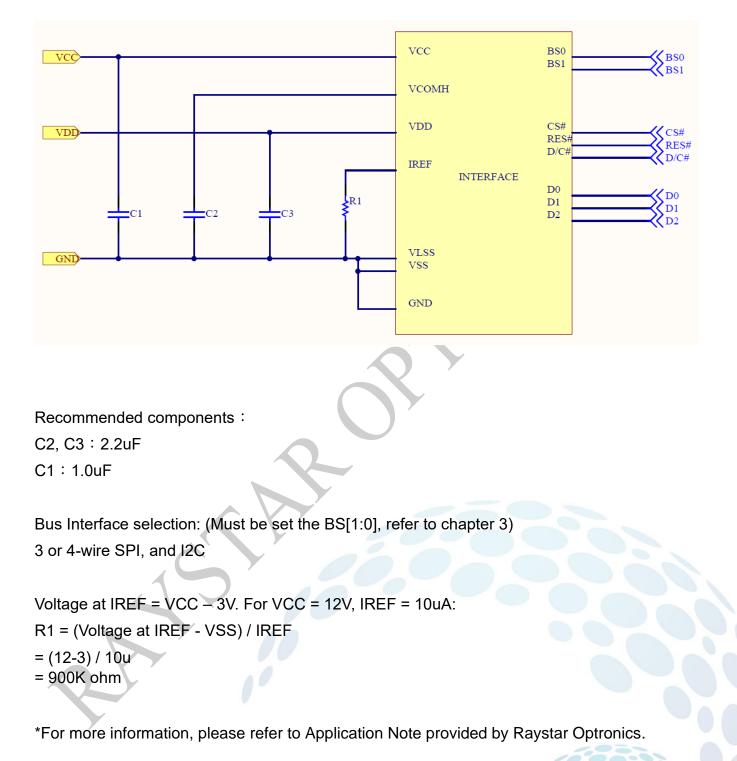




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#### 4.1 Application recommendations





### **5.Absolute Maximum Ratings**

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4.0	V	1,2
Supply Voltage for Display	VCC	0	16.0	V	1,2
Operating Temperature	TOP	-40	+80	°C	5
Storage Temperature	TSTG	-40	+85	°C	

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.



### **6.Electrical Characteristics**

### 6.1 DC Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	—	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	—	11.5	12.0	12.5	V
High Level Input	VIH		0.8×VDD	T	_	V
Low Level Input	VIL		0	) í	0.2×VDD	V
High Level Output	VOH	- 🗸	0.9×VDD	_	_	V
Low Level Output	VOL		-		0.1×VDD	V
Operating Current for VCC (Full ON)	ICC	VCC=12.0V	_	11	16.5	mA



#### 6.2 Initial code

}

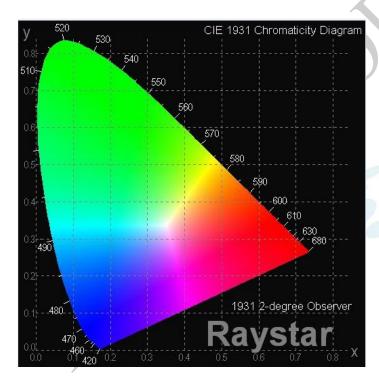
void Initial\_SSD1307ZD(void){

Write\_command(0xAE); // Display Off Write command(0xD5); //SET DISPLAY CLOCK Write\_command(0x80); // Write\_command(0xA8); // Select Multiplex Ratio Write command(0x1F); // Default => 0x3F (1/64 Duty) 0x1F(1/32 Duty) Write command(0xD3); //Setting Display Offset Write command(0x00); //00H Reset Write\_command(0x40); //Set Display Start Line Write\_command(0xA1); //Set Segment Re-Map Default //0xA0 (0x00) => column Address 0 mapped to 127 //0xA1 (0x01) => Column Address 127 mapped to 0 Write\_command(0xC0); //Set COM Output Scan Direction Write\_command(0xDA); //Set COM Hardware Configuration Write\_command(0x12); //Alternative COM Pin---See IC Spec page 34 Write\_command(0x81); //Set Contrast Control Write\_command(0x48); Write\_command(0xD9); //Set Pre-Charge period Write\_command(0xA1); Write\_command(0xDB); //Set Deselect Vcomh level Write command(0x00); Write command(0xA4); //Entire Display ON Write\_command(0xA6); //Set Normal Display Write\_command(0xAF); // Display ON



### **7.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
	(V)θ	_	160	_	_	deg
View Angle	(H)φ	_	160	_		deg
Contrast Ratio	CR	Dark	2000:1	- 🗸	—	) —
	T rise	_	_	10		μs
Response Time	T fall	_	-	10	_	μs
Display with 100%	o check Board Br	ightness	160     -       160     -       2000:1     -       -     10	cd/m2		
CIEx(Yellow) (CIE1931			0.45	0.47	0.49	_
CIEy(Yellov	N)	(CIE1931)	0.48	0.50	0.52	_





### 8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness 100cd/ m²	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



### 9.Reliability

#### Content of Reliability Test

Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	- (
₋ow Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
ligh ēmperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	1
₋ow ſemperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Femperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	
Femperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min <u>5mjn 30min</u>	-40°C /80°C 30 cycles	
Aechanical Te	st C		
/ibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	
Others	· · · · · · · · · · · · · · · · · · ·	1	
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	_

\*\*\* Supply voltage for OLED system =Operating voltage at 25°C



#### Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels on/off exchange is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

#### **Evaluation criteria**

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

#### **APPENDIX:**

#### **RESIDUE IMAGE**

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



### **10.Inspection specification**

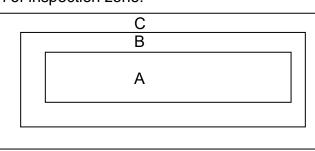
#### **Inspection Standard:**

MIL-STD-105E table normal inspection single sample level II.

#### Definition

1 Major defect : The defect that greatly affect the usability of product.

2 Minor defect : The other defects, such as cosmetic defects, etc. Definition of inspection zone:



Zone A: Active Area

Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

#### **Inspection Methods**

- 1 The general inspection : Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.
- 2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal equipments, in the dark room, under 25±5°C.

NO	Item	Criterion	AQL
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 OLED viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>	0.65
02	Black or white spots on OLED (display only)	<ul> <li>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm.</li> </ul>	2.5



NO	Item		Criterio	n			AQL
	OLED black spots, white spots, contamin ation (non- display)	3.1 Round type : As following drawing $\Phi=(x + y) / 2$	$\begin{tabular}{ c c c c c } SIZE \\ \hline \Phi \leq 0.10 \\ \hline 0.10 < \Phi \leq 0.20 \\ \hline 0.20 < \Phi \leq 0.25 \\ \hline 0.25 < \Phi \end{tabular}$		Acceptable QTY ignore 2 1 0	Zone A+ B, A+ B A+ B A+ B	2.5
03		3.2 Line type : (As		)	Acceptable Q TY	Zone	2.5
			W≦0.02		ignore	A+B	
		L≦3.0		03	Ŭ	A+B	
		L≦2.	5 0.03 <w≦0.< td=""><td>05</td><td>2</td><td>A+B</td><td></td></w≦0.<>	05	2	A+B	
			0.05 <w< td=""><td></td><td>As round type</td><td></td><td></td></w<>		As round type		
			Y		50;		
		4.1 If bubbles	Size Φ		cceptable Q TY	Zone	
		are visible, judge	Φ≦0.20	A	ignore	Zone A+B	
	Polarizer	using black spot	Φ <u>≦</u> 0.20 0.20<Φ≦0.50		3	A+B	
04	bubbles	specifications,	$0.20 < \Phi \le 0.30$ $0.50 < \Phi \le 1.00$	+	2	A+B A+B	2.5
	/Dent	not easy to find,	0.00 < Φ <u>1.00</u>	+	0	A+B	
		must check in	Total Q TY		3		
	L'	specify direction. 4.2 The polarizer d		pecif			
05	Scratches	Follow NO.3 OLED	) black spots, whit	te sp	oots, contaminati	on.	



NO	ltem	Criterion	AQL
	Chipped glass	Symbols Define: x: Chip length k: Seal widthy: Chip width t: Glass thickness 	2.5
06		6.1.2 Corner crack: $x$ $z$ $y$ $z$	2.5
	Glass crack	Symbols : x: Chip lengthy: Chip widthz: Chip thicknessk: Seal widtht: Glass thicknessa: OLED side lengthL: Electrode pad length6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :LLLLVLVLVLVLVXY: Chip widthx: Chip lengthx \le 1/8a0 < z \le t	2.5
			6



NO	Item	Criterion	AQL
06	Glass crack	6.2.2 Non-conductive portion:         y         x         y         x         y         x         y         y         x         y	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65



NO	Item	Criterion	AQL
	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
10		<ul><li>10.2 COB seal surface may not have pinholes through to the IC.</li><li>10.3 The height of the COB should not exceed the height</li></ul>	2.5 0.65
		indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than	2.5
		<ul> <li>three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts,</li> </ul>	2.5 0.65
		missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
14	Soldering	<ul><li>11.1 No un-melted solder paste may be present on the PCB.</li><li>11.2 No cold solder joints, missing solder connections,</li></ul>	2.5 2.5
11		oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 0.65
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		<ul> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> </ul>	0.65 2.5
12		<ul> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> </ul>	2.5 2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		<ul><li>12.7 Sealant on top of the ITO circuit has not hardened.</li><li>12.8 Pin type must match type in specification sheet.</li><li>12.9 OLED pin loose or missing pins.</li></ul>	2.5 0.65 0.65
		<ul><li>12.10 Product packaging must the same as specified on packaging specification sheet.</li><li>12.11 Product dimension and structure must conform to product specification sheet.</li></ul>	0.65 0.65
	<u> </u>	Page 22 , Total 28 Pages	<u> </u>



Check Item	Classification	Criteria		
No Display	Major			
Missing Line	Major			
Pixel Short	Major			
Darker Short	Major			
Wrong Display	Major			
Un-uniform /A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel		

N



## **11.Precautions in use of OLED Modules**

### Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.

#### 11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.

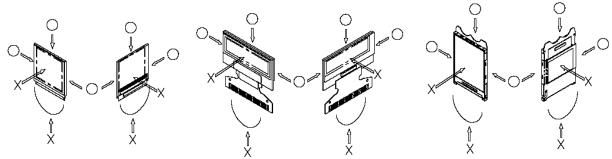
\* Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy. Also, pay attention that the following liquid and solvent may spoil the polarizer:

- \* Water
- \* Ketone
- \* Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
  - \* Pins and electrodes
  - \* Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the



System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
  - \* Be sure to make human body grounding when handling OLED display modules.
  - \* Be sure to ground tools to use or assembly such as soldering irons.

\* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.

\* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

#### 11.2. Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. And, also, place in the temperature 25±5°C and Humidity below 65% RH.(We recommend you to store these modules in the packaged state when they were shipped from Winstar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

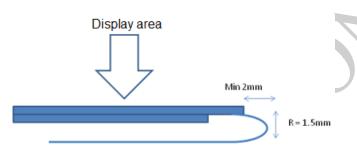
#### 11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.

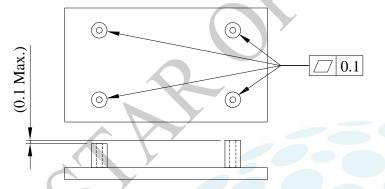


\* Connection (contact) to any other potential than the above may lead to rupture of the IC.

- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The limitation of FPC and Film bending.



(12) The module should be fixed balanced into the housing, or the module may be twisted.



(13) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

#### 11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.





		Page: 1
Modul	le Sample	Estimate Feedback Sheet
Module Number :		
1 <u> Panel Specification</u> :		
1. Panel Type:	Pass	□NG ,
2. Numbers of Pixel :	Pass	□NG ,
3. View Area ∶	Pass	□NG ,
4. Active Area :	Pass	□NG ,
5.Emitting Color :	Pass	□NG ,
6.Uniformity :	□Pass	□NG ,
7.Operating	Pass	□NG ,
Temperature :		
8.Storage	Pass	□NG ,
Temperature :		
9.Others :		
2 · <u>Mechanical Specificat</u>	ion :	
1. PCB Size :	□Pass	□NG ,
2.Frame Size:	□Pass	□NG ,
3.Materal of Frame :	□Pass	□NG ,
4.Connector Position :	□Pass	□NG ,
5.Fix Hole Position :	□Pass	□NG ,
6. Thickness of PCB :	□Pass	∕⊡NG ,
7. Height of Frame to	□Pass	□NG ,
PCB :		
8.Height of Module :	□Pass	□NG ,
9.Others :	□Pass	□NG ,
3 · <u>Relative Hole Size</u> :		
1.Pitch of Connector :	□Pass	□NG ,
2.Hole size of	□Pass	□NG ,
Connector :		
3.Mounting Hole size :	□Pass	□NG ,
4.Mounting Hole Type :	□Pass	□NG ,
5.Others :	□Pass	□NG ,
	>>	Go to page 2 <<



		Page:
Module Number : 4 、 <u>Electronic Characterist</u>	ics of Mod	
1.Input Voltage :	□Pass	DNG ,
2.Supply Current :		□NG ,
3.Driving Voltage for	□Pass	□NG ,
OLED :		
4.Contrast for OLED :	□Pass	□NG ,
5.Negative Voltage	□Pass	□NG ,
Output: 6.Interface Function:	□Pass	
7.ESD test :		
8.Others :		□NG , □NG ,
5 · <u>Summary</u> :	UF ass	
	R	
Sales signature : _		
Sales signature : Customer Signature	e:	Date : / /